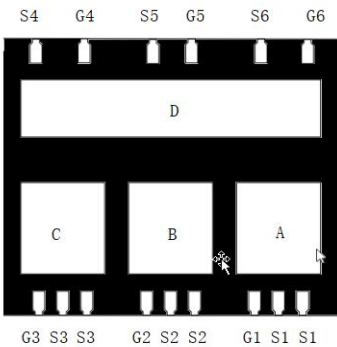




CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD
DFN14*12 Plastic-Encapsulate MOSFETS

CCM80N10-6A Full bridge N Channel MOSFET

| | | |
|---------------|-----------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(on)TYP}$ | I_D |
| 40 V | 8.0mΩ@10V | 80A |



DESCRIPTION

The CCM80N10-6A provides excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

FEATURE

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- AEC Q101 qualified

APPLICATION

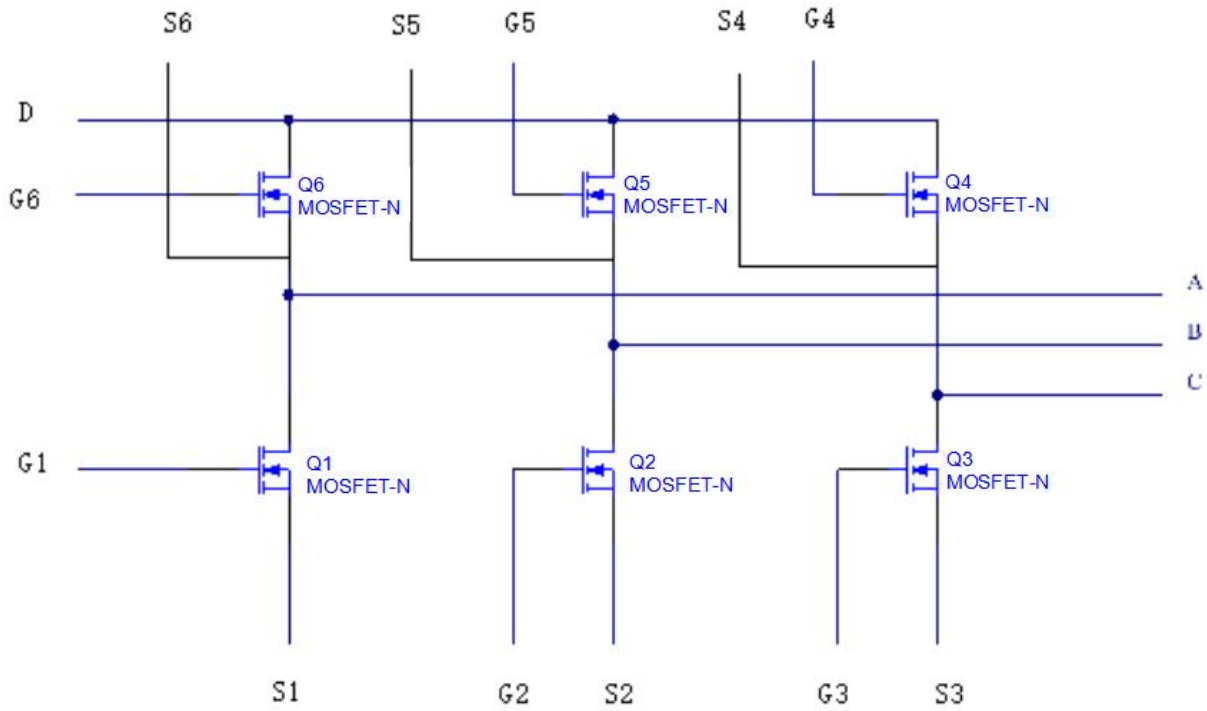
- motor control
- Full bridge module

MARKING



CCM80N10-6A =Part No.
 XXXXXXXX = Code

EQUIVALENT CIRCUIT



Pin Definition

| Number | Pin Definition | Remark | Number | Pin Definition | Remark |
|--------|----------------|--|--------|----------------|--|
| 1 | S1 | Lower bridge u phase source | 11 | G4 | Upper bridge w gate |
| 2 | S1 | Lower bridge u phase source | 12 | S5 | Upper Bridge v phase source collection |
| 3 | G1 | Lower bridge u phase gate | 13 | G5 | Upper bridge v gate |
| 4 | S2 | Lower bridge v phase source | 14 | S6 | Upper Bridge u phase source collection |
| 5 | S2 | Lower bridge v phase source | 15 | G6 | Upper bridge u gate |
| 6 | G2 | Lower bridge v phase gate | PAD 1 | D | DC Input |
| 7 | S3 | Lower bridge w phase source | PAD 2 | A | A phase output |
| 8 | S3 | Lower bridge w phase source | PAD 3 | B | B phase output |
| 9 | G3 | Lower bridge w phase gate | PAD 4 | C | C phase output |
| 10 | S4 | Upper Bridge w phase source collection | | | |

ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|-------------------|----------|------|
| Drain-Source Voltage | V _{DS} | 100 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Continuous Drain Current ¹ | I _D | 80 | A |
| Pulsed Drain Current ² | I _{DM} | 320 | A |
| Single Pulsed Avalanche Energy ³ | EAS | 240 | mJ |
| Total Power Dissipation | P _D | 115 | W |
| Thermal Resistance from Junction to Case ¹ | R _{thJC} | 1.3 | °C/W |
| Junction Temperature | T _J | 175 | °C |
| Storage Temperature | T _{stg} | -55~+175 | °C |
| Soldering Temperature , for 10S(1.6mm from case) | - | 260 | °C |

Notes :

1. Current is limited by package; with a R_{thjc} = 1.3 °C/W the chip is able to carry 85 A at 25°C.
2. Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
3. EAS condition: VDD = 20V, VGS = 10V, L = 0.5mH, R_G = 25Ω, I_{as}=31A, Starting T_J = 25°C.

MOSFET ELECTRICAL CHARACTERISTICS

TC=25°C unless otherwise specified

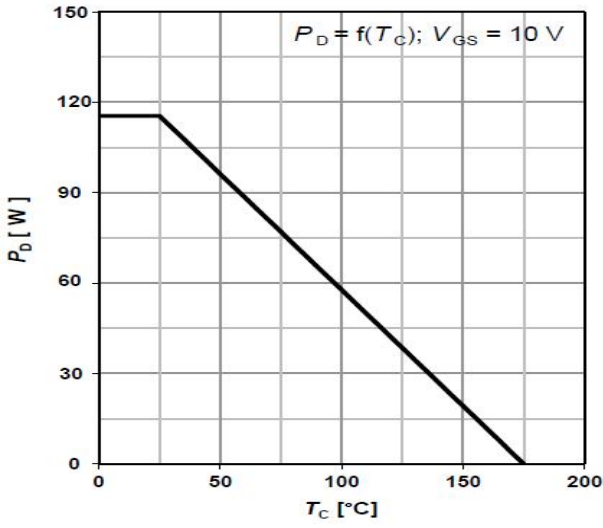
| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|--|---------------|--|-----|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain - Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 100 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 100V, V_{GS} = 0V$ | | | 1 | μA |
| Gate - Body Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ± 100 | nA |
| On Characteristics³ | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2.0 | 3.3 | 4.0 | V |
| Drain-source On-resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 40A$ | | 8.0 | 10 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS} = 10V, I_D = 40A$ | | 65 | | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$ | | 2183 | 2850 | pF |
| Output Capacitance | C_{oss} | | | 1007 | 1350 | |
| Reverse Transfer Capacitance | C_{rss} | | | 89 | 120 | |
| Gate Resistance | R_g | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$ | | 2.1 | | Ω |
| Switching Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{DD} = 20V, V_{GS} = 10V, I_D = 80A$ | | 43 | | nC |
| Gate-source Charge | Q_{gs} | | | 15 | | |
| Gate-drain Charge | Q_{gd} | | | 9 | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD} = 20V, V_{GS} = 10V, R_L = 1\Omega, R_G = 3\Omega$ | | 18 | | ns |
| Turn-on Rise Time | t_r | | | 42 | | |
| Turn-off Delay Time | $t_{d(off)}$ | | | 31 | | |
| Turn-off Fall Time | t_f | | | 8 | | |
| Source - Drain Diode Characteristics | | | | | | |
| Diode Forward Voltage ³ | V_{SD} | $V_{GS} = 0V, I_S = 80A$ | | | 1.2 | V |
| Continuous drain-source diode forward Current ¹ | I_S | - | | | 80 | A |
| Pulsed drain-source diode forward current ² | I_{SM} | - | | | 320 | A |
| Reverse recovery time | T_{rr} | $V_r=50V, I_F=80A, di/dt=100A/us$ | | 71 | | ns |
| Reverse recovery charge | Q_{rr} | | | 123 | | nC |

Notes :

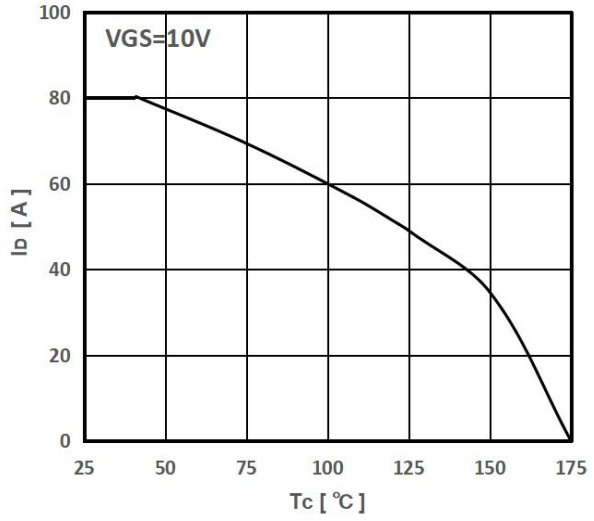
1. Current is limited by package; with a $R_{thjc} = 1.3 \text{ }^\circ C/W$ the chip is able to carry 85 A at 25°C.
2. $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$.
3. Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Typical Characteristics

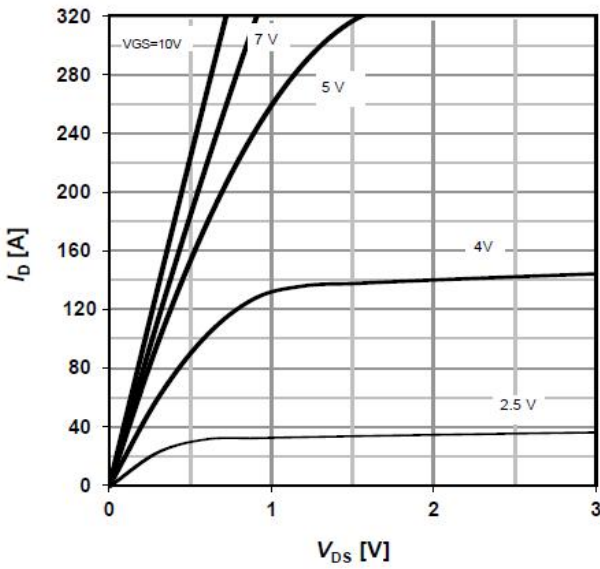
PD-Tc



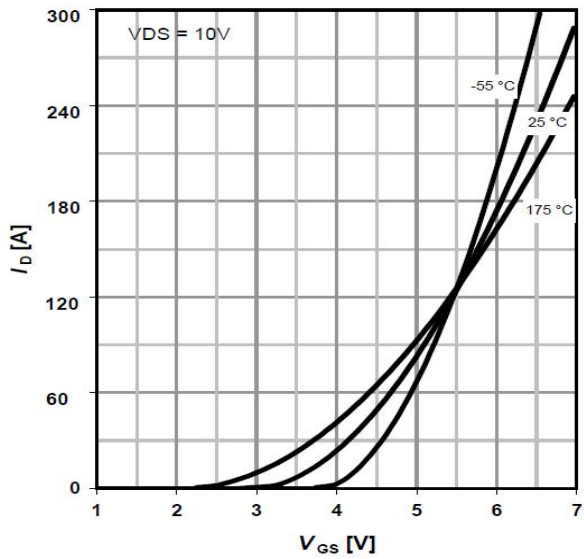
ID - Tc



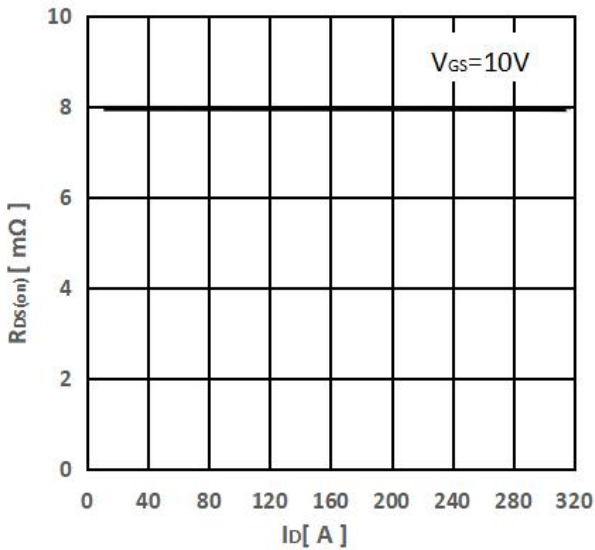
ID - VDS



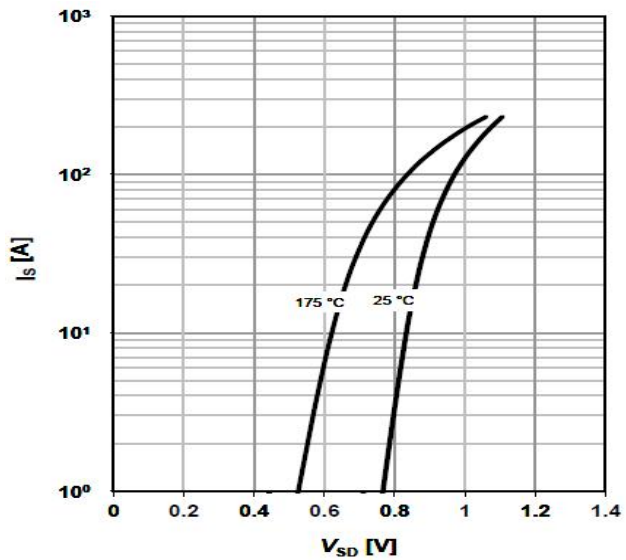
ID - VGS



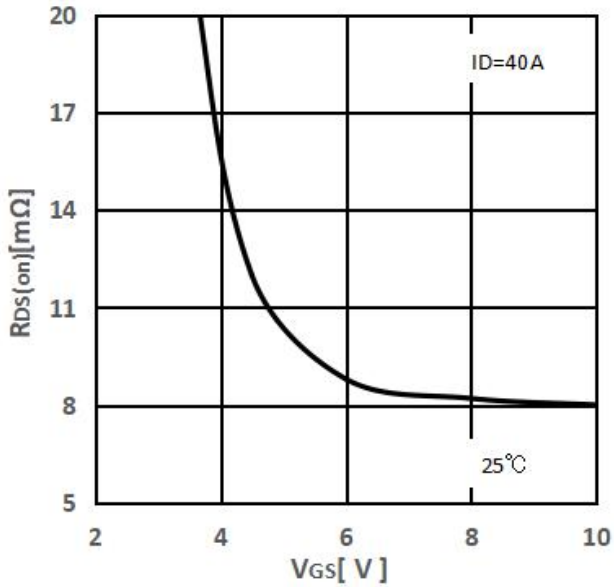
RDS(on) - ID



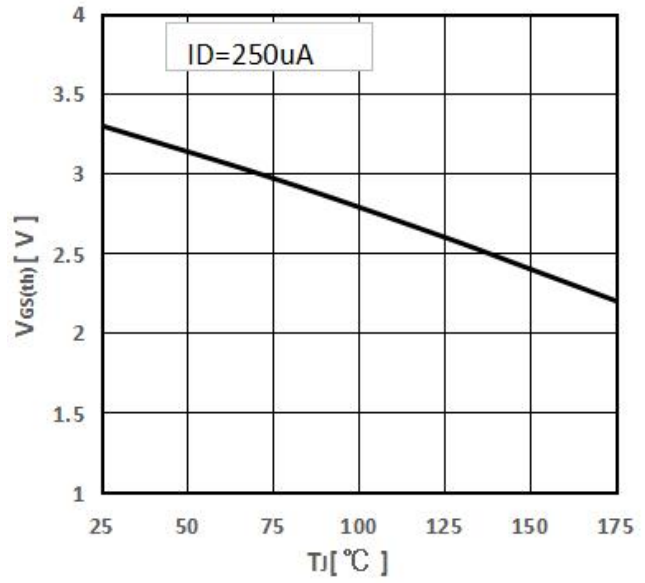
IS - VSD



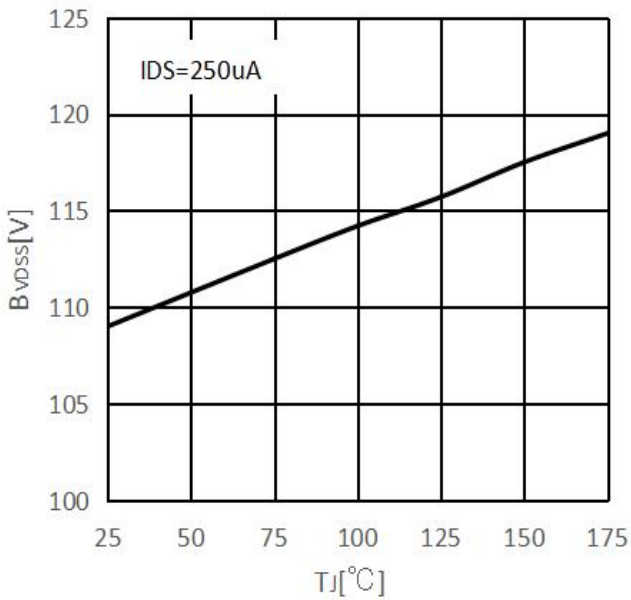
RDS(on) -- VGS



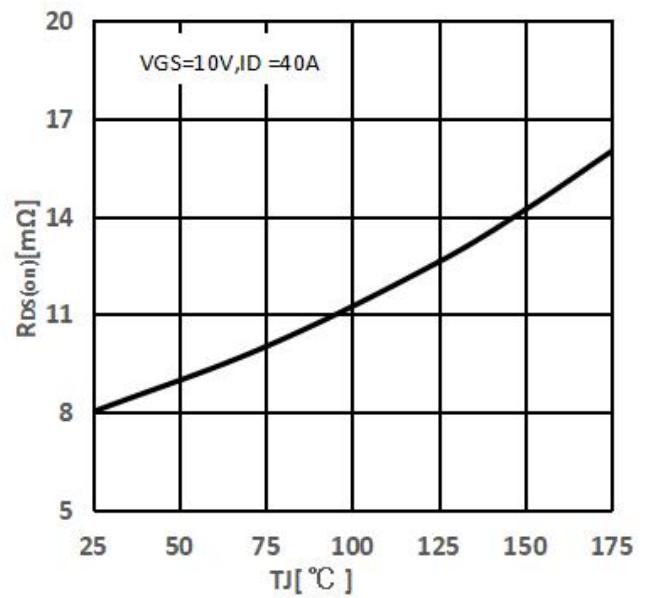
Threshold Voltage



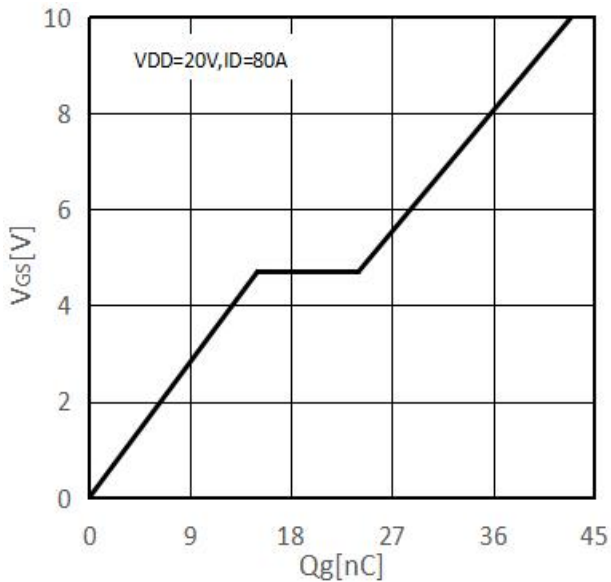
Drain-source breakdown voltage



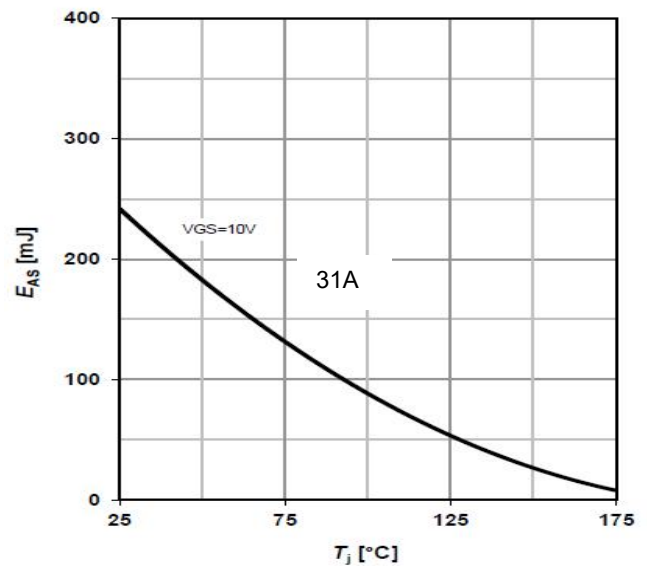
RDS(on) -- TJ



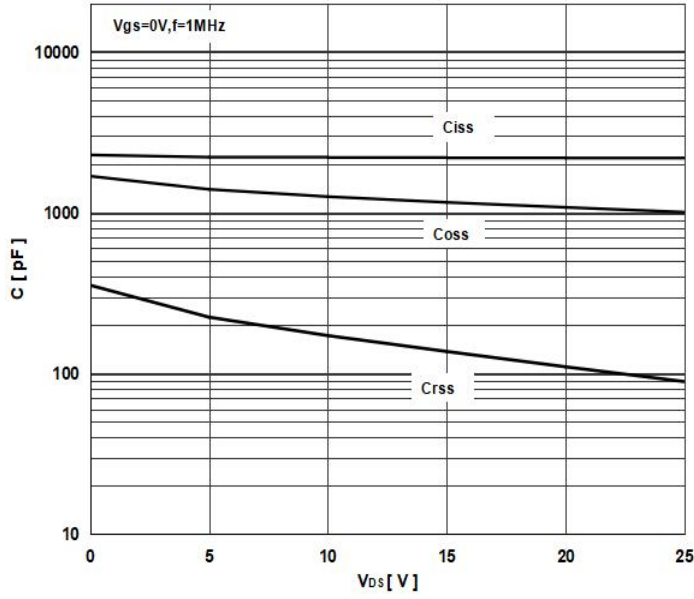
Typ.gate charge



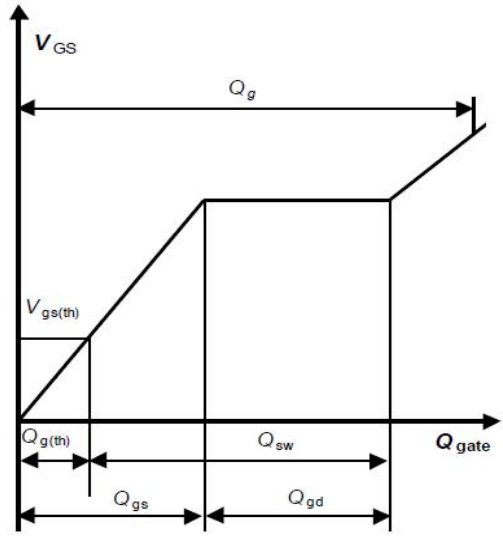
Avalanche energy



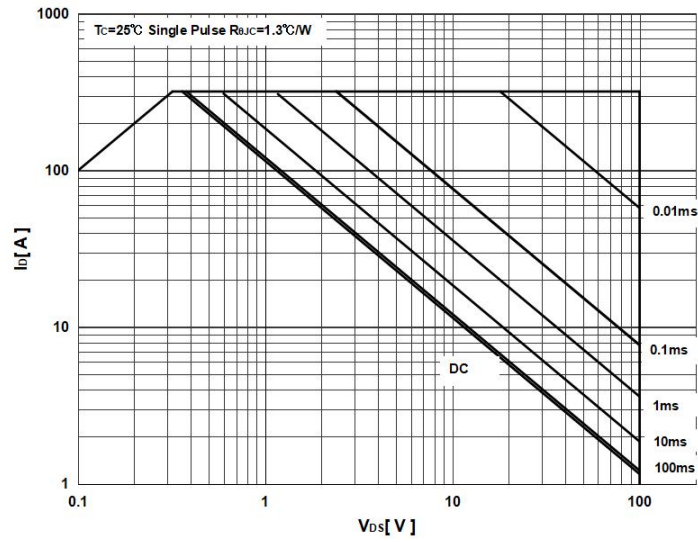
Typ. capacitances



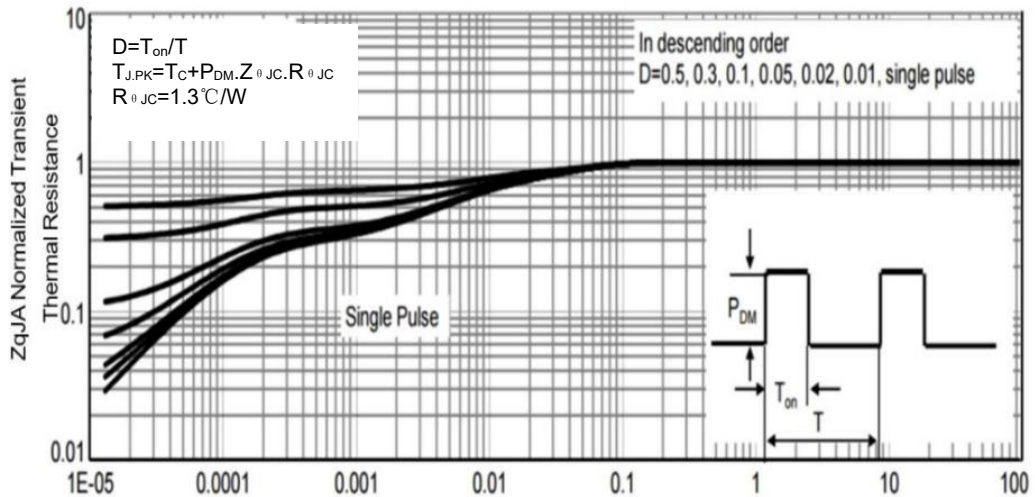
Gate charge waveforms



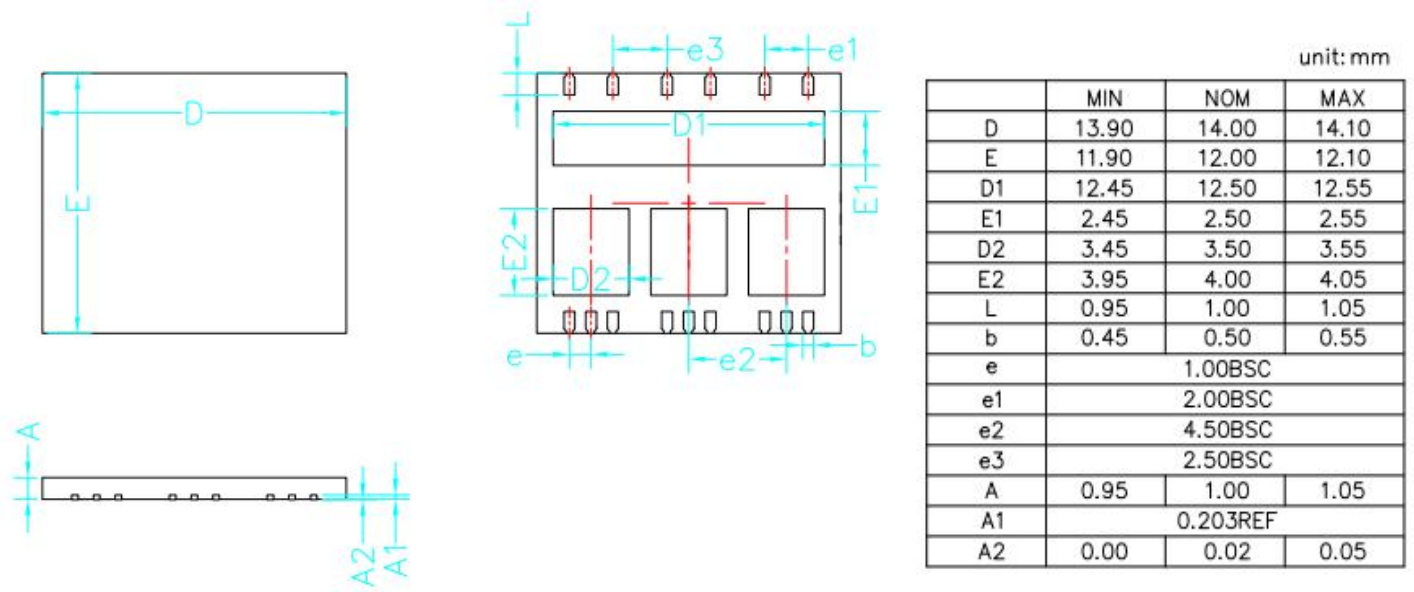
Maximum Forward Biased Safe Operating Area



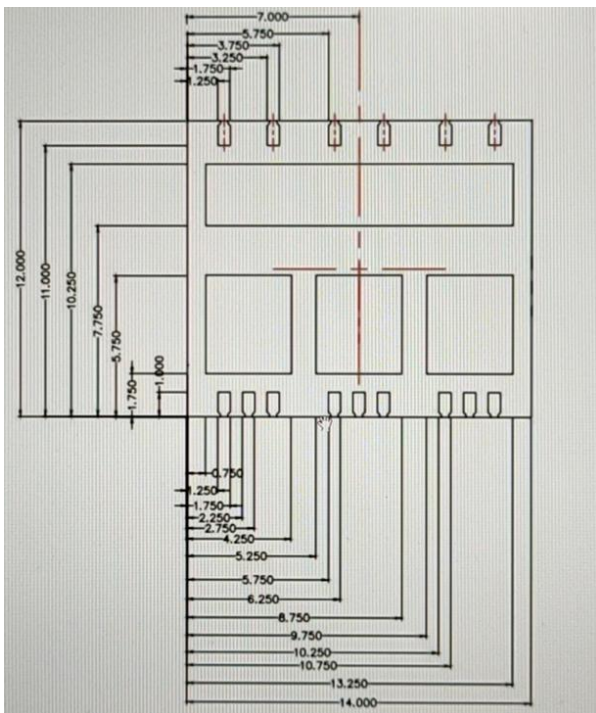
Normalized Thermal Transient Impedance



DFN14*12 Package Outline Dimensions



DFN14*12 Suggested Pad Layout



Note:

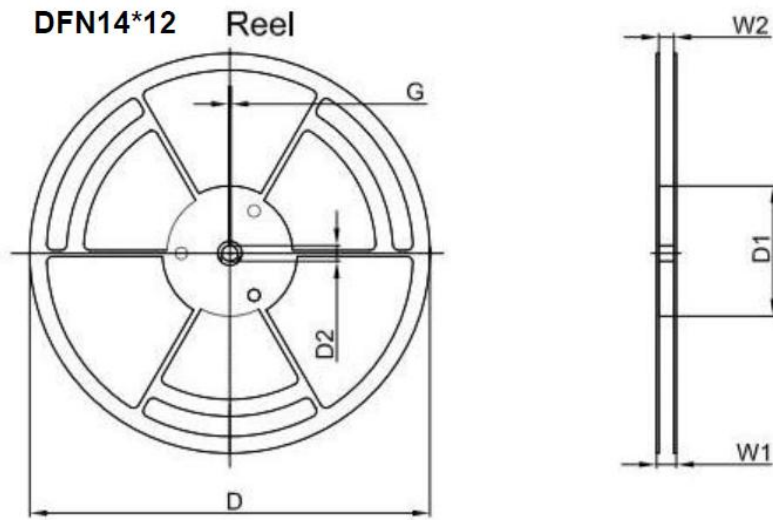
1. Controlling dimension: in millimeters.
2. General tolerance: 0.5mm.
3. The pad layout is for reference purposes only.

NOTICE

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DFN14*12 Tape and Reel



| Dimensions are in millimeter | | | | | | |
|------------------------------|---------|--------|-------|------|-------|-------|
| Reel Option | D | D1 | D2 | G | W1 | W2 |
| 13"D1a | Ø330,00 | 100,00 | 13,00 | 1,90 | 28,40 | 24,00 |

| REEL | Reel Size | Box | Box Size(mm) | Carton | Carton Size(mm) |
|-----------|-----------|-----------|--------------|------------|-----------------|
| 2,000 pcs | 13 inch | 4,000 pcs | 340×336×29 | 20,000 pcs | 353×346×365 |

| Date of change | Rev # | revise content |
|----------------|-------|----------------|
| 2024/02/25 | A/0 | / |
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